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#### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Active
Core Processor	S12Z
Core Size	16-Bit
Speed	32MHz
Connectivity	CANbus, I <sup>2</sup> C, IrDA, LINbus, SCI, SPI, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	96КВ (96К х 8)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	5.5V ~ 18V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s912zvl96f0mlfr

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	18.4.3 Data Format	
	18.4.4 Baud Rate Generation	
	18.4.5 Transmitter	
	18.4.6 Receiver	
	18.4.7 Single-Wire Operation	
	18.4.8 Loop Operation	
18.5	Initialization/Application Information	
	18.5.1 Reset Initialization	
	18.5.2 Modes of Operation	
	18.5.3 Interrupt Operation	
	18.5.4 Recovery from Wait Mode	541
	18.5.5 Recovery from Stop Mode	541

# Chapter 19 Serial Peripheral Interface (S12SPIV5)

19.1	Introduc	ction	543
	19.1.1	Glossary of Terms	543
	19.1.2	Features	543
	19.1.3	Modes of Operation	543
	19.1.4	Block Diagram	544
19.2	External	l Signal Description	545
	19.2.1	MOSI — Master Out/Slave In Pin	545
	19.2.2	MISO — Master In/Slave Out Pin	546
	19.2.3	$\overline{SS}$ — Slave Select Pin	546
	19.2.4	SCK — Serial Clock Pin	546
19.3	Memory	y Map and Register Definition	546
	19.3.1	Module Memory Map	546
	19.3.2	Register Descriptions	547
19.4	Function	nal Description	555
	19.4.1	Master Mode	556
	19.4.2	Slave Mode	557
	19.4.3	Transmission Formats	558
	19.4.4	SPI Baud Rate Generation	563
	19.4.5	Special Features	564
	19.4.6	Error Conditions	565
	19.4.7	Low Power Mode Options	566

# Chapter 20

# Inter-Integrated Circuit (IICV3)

20.1	Introduction	569
	20.1.1 Features	569
	20.1.2 Modes of Operation	570
	20.1.3 Block Diagram	570
20.2	External Signal Description	570

- Broadcast mode support
- 10-bit address support

## 1.4.8 LIN physical layer transceiver

- Compliant with LIN Physical Layer 2.2 specification
- Compliant with the SAE J2602-2 LIN standard
- Standby mode with glitch-filtered wake-up
- Slew rate selection optimized for the baud rates: 10.4kBit/s, 20kBit/s and Fast Mode (up to 250kBit/s)
- Switchable  $34k\Omega/330k\Omega$  pull-ups
- Current limitation for LIN Bus pin falling edge
- Over-current protection
- LIN TxD-dominant timeout feature monitoring the LPTxD signal
- Automatic transmitter shutdown in case of an over-current or TxD-dominant timeout
- Fulfills the OEM "Hardware Requirements for LIN (CAN and FlexRay) Interfaces in Automotive Applications" v1.3

## **1.4.9** Serial Communication Interface Module (SCI)

- Full-duplex or single-wire operation
- Standard mark/space non-return-to-zero (NRZ) format
- Selectable IrDA 1.4 return-to-zero-inverted (RZI) format with programmable pulse widths
- Baud rate generator by a 16-bit divider from the bus clock
- Programmable character length
- Programmable polarity for transmitter and receiver
- Active edge receive wakeup
- Break detect and transmit collision detect supporting LIN

# 1.4.10 Serial Peripheral Interface Module (SPI)

- Configurable 8- or 16-bit data size
- Full-duplex or single-wire bidirectional
- Double-buffered transmit and receive
- Master or slave mode
- MSB-first or LSB-first shifting
- Serial clock phase and polarity options

# 1.4.11 Multi-Scalable Controller Area Network (MSCAN)

• Implementation of CAN protocol - Version 2.0A/B

	-				
Vector Address <sup>1</sup>	Interrupt Source	CCR Mask	Local Enable	Wake up from STOP	Wake up from WAIT
Vector base + 0x1CC	TIM0 timer channel 0	l bit	TIMOTIE (COI)	No	Yes
Vector base + 0x1C8	TIM0 timer channel 1	l bit	TIM0TIE (C1I)	No	Yes
Vector base + 0x1C4	TIM0 timer channel 2	l bit	TIM0TIE (C2I)	No	Yes
Vector base + 0x1C0	TIM0 timer channel 3	l bit	TIM0TIE (C3I)	No	Yes
Vector base + 0x1BC	TIM0 timer channel 4	l bit	TIM0TIE (C4I)	No	Yes
Vector base + 0x1B8	TIM0 timer channel 5	l bit	TIM0TIE (C5I)	No	Yes
Vector base + 0x1B4 to Vector base + 0x1B0			Reserved		
Vector base + 0x1AC	TIM0 timer overflow	l bit	TIM0TSCR2(TOI)	No	Yes
Vector base + 0x1A8 to Vector base + 0x1A4			Reserved		
Vector base + 0x1A0	SPI0	l bit	SPI0CR1 (SPIE, SPTIE)	No	Yes
Vector base + 0x19C	SCI0	l bit	SCI0CR2 (TIE, TCIE, RIE, ILIE) SCI0ACR1 (RXEDGIE, BERRIE, BKDIE)	RXEDGIF only	Yes
Vector base + 0x198	SCI1	l bit	SCI1CR2 (TIE, TCIE, RIE, ILIE) SCI1ACR1 (RXEDGIE, BERRIE, BKDIE)	RXEDGIF only	Yes
Vector base + 0x194 to Vector base + 0x190			Reserved		
Vector base + 0x18C	ADC Error	l bit	ADCEIE (IA_EIE, CMD_EIE, EOL_EIE, TRIG_EIE, RSTAR_EIE, LDOK_EIE) ADCIE(CONIF_OIE)	No	Yes
Vector base + 0x188	ADC conversion sequence abort	l bit	ADCIE(SEQAD_IE)	No	Yes
Vector base + 0x184	ADC conversion complete	l bit	ADCCONIE[15:0]	No	Yes
Vector base + 0x180	Oscillator status interrupt	l bit	CPMUINT (OSCIE)	No	Yes
Vector base + 0x17C	PLL lock interrupt	l bit	CPMUINT (LOCKIE)	No	Yes
Vector base + 0x178	ACMP	l bit	ACMPC(ACIE)	No	Yes
Vector base + 0x174 to Vector base + 0x174			Reserved		
Vector base + 0x170	RAM error	l bit	EECIE (SBEEIE)	No	Yes

### Table 1-12. Interrupt Vector Locations (Sheet 2 of 4)

Command Mnemonic	Command Classification	ACK	Command Structure	Description
READ_SAME.sz	Non-Intrusive	Yes	(0x50+4 x sz)/dack/rd.sz	Read from location. An initial READ_MEM defines the address, subsequent READ_SAME reads return content of same address
READ_SAME.sz_WS	Non-Intrusive	No	(0x51+4 x sz)/d/ss/rd.sz	Read from location. An initial READ_MEM defines the address, subsequent READ_SAME reads return content of same address
READ_BDCCSR	Always Available	No	0x2D/rd16	Read the BDCCSR register
SYNC_PC	Non-Intrusive	Yes	0x01/dack/rd24	Read current PC
WRITE_MEM.sz	Non-Intrusive	Yes	(0x10+4 x sz)/ad24/wd.sz/dack	Write the appropriately-sized (sz) memory value to the location specified by the 24-bit address
WRITE_MEM.sz_WS	Non-Intrusive	No	(0x11+4 x sz)/ad24/wd.sz/d/ss	Write the appropriately-sized (sz) memory value to the location specified by the 24-bit address and report status
WRITE_Rn	Active Background	Yes	(0x40+CRN)/wd32/dack	Write the requested CPU register
WRITE_BDCCSR	Always Available	No	0x0D/wd16	Write the BDCCSR register
ERASE_FLASH	Always Available	No	0x95/d	Mass erase internal flash
STEP1 (TRACE1)	Active Background	Yes	0x09/dack	Execute one CPU command.

<sup>1</sup> The SYNC command is a special operation which does not have a command code.

<sup>2</sup> The GO\_UNTIL command is identical to the GO command if ACK is not enabled.

## 5.4.4.1 SYNC

The SYNC command is unlike other BDC commands because the host does not necessarily know the correct speed to use for serial communications until after it has analyzed the response to the SYNC command.

To issue a SYNC command, the host:

- 1. Ensures that the BKGD pin is high for at least 4 cycles of the slowest possible BDCSI clock without reset asserted.
- 2. Drives the BKGD pin low for at least 128 cycles of the slowest possible BDCSI clock.
- 3. Drives BKGD high for a brief speed-up pulse to get a fast rise time. (This speedup pulse is typically one cycle of the host clock which is as fast as the maximum target BDCSI clock).
- 4. Removes all drive to the BKGD pin so it reverts to high impedance.
- 5. Listens to the BKGD pin for the sync response pulse.

#### Background Debug Controller (S12ZBDCV2)

0x32		Data[7-0]				
host → target	D A C K	target → host				
0x36		Data[15-8]	Data[7-0]			
host → target	D A C K	target → host	target → host			
0x3A		Data[31-24]	Data[23-16]	Data[15-8]	Data[7-0]	
host → target	D A C K	target → host	target → host	target → host	target → host	

# DUMP\_MEM.sz\_WS

DUMD MEM er

Read memory specified by debug address register with status, Non-intrusive then increment address

	0x33		BDCCSRL	Data[7-0]			
	host → target	D L Y	target → host	target $\rightarrow$ host			
	0x37		BDCCSRL	Data[15-8]	Data[7-0]		
-	host → target	D L Y	target → host	target → host	target $\rightarrow$ host		
	0x3B		BDCCSRL	Data[31-24]	Data23-16]	Data[15-8]	Data[7-0]
-	host $\rightarrow$ target	D L Y	target $\rightarrow$ host				

DUMP\_MEM{\_WS} is used with the READ\_MEM{\_WS} command to access large blocks of memory. An initial READ\_MEM{\_WS} is executed to set-up the starting address of the block and to retrieve the first result. The DUMP\_MEM{\_WS} command retrieves subsequent operands. The initial address is incremented by the operand size (1, 2, or 4) and saved in a temporary register. Subsequent DUMP\_MEM{\_WS} commands use this address, perform the memory read, increment it by the current operand size, and store the updated address in the temporary register. If the with-status option is specified, the BDCCSRL status byte is returned before the read data. This status byte reflects the state after the memory read was performed. If enabled, an ACK pulse is driven before the data bytes are transmitted. The effect of the access size and alignment on the next address to be accessed is explained in more detail in Section 5.4.5.2, "BDC Access Of Device Memory Mapped Resources".

### NOTE

DUMP\_MEM{\_WS} is a valid command only when preceded by SYNC, NOP, READ\_MEM{\_WS}, or another DUMP\_MEM{\_WS} command. Otherwise, an illegal command response is returned, setting the ILLCMD bit. NOP can be used for inter-command padding without corrupting the address pointer.

The size field (sz) is examined each time a DUMP\_MEM{\_WS} command is processed, allowing the operand size to be dynamically altered. The examples show the DUMP\_MEM.B{\_WS}, DUMP\_MEM.W{\_WS} and DUMP\_MEM.L{\_WS} commands.

### 5.4.4.6 FILL\_MEM.sz, FILL\_MEM.sz\_WS

#### FILL\_MEM.sz

Write memory specified by debug address register, then increment address Non-intrusive



#### FILL\_MEM.sz\_WS

Write memory specified by debug address register with status, then increment address **Non-intrusive** 

0x13	Data[7-0]		BDCCSR	L		
host → target	host → target	D L Y	target → host			
0x17	Data[15-8]		Data[7-0]		BDCCSRL	
host → target	host → target		host → target	D L Y	target → host	_

S12Z DebugLite (S12ZDBGV3)

Address	Name		Bit 7	6	5	4	3	2	1	Bit 0	
0x0111-	Reserved	R	0	0 0 0 0 0 0 0 0							
0x0114		W									
0x0115	DBGAAH	R W				DBGAA	A[23:16]				
0x0116	DBGAAM	R W				DBGA	A[15:8]				
0x0117	DBGAAL	R W				DBGA	A[7:0]				
0x0118	DBGAD0	R W	Bit 31	30	29	28	27	26	25	Bit 24	
0x0119	DBGAD1	R W	Bit 23	22	21	20	19	18	17	Bit 16	
0x011A	DBGAD2	R W	Bit 15	14	13	12	11	10	9	Bit 8	
0x011B	DBGAD3	R W	Bit 7	6	5	4	3	2	1	Bit 0	
0x011C	DBGADM0	R W	Bit 31	30	29	28	27	26	25	Bit 24	
0x011D	DBGADM1	R W	Bit 23	22	21	20	19	18	17	Bit 16	
0x011E	DBGADM2	R W	Bit 15	14	13	12	11	10	9	Bit 8	
0x011F	DBGADM3	R W	Bit 7	6	5	4	3	2	1	Bit 0	
0x0120	DBGBCTL	R W	0	0	INST	0	RW	RWE	reserved	COMPE	
0x0121-	Reserved	R	0	0	0	0	0	0	0	0	
0x0124	Reserved	W									
0x0125	DBGBAH	R W		DBGBA[23:16]							
0x0126	DBGBAM	R W		DBGBA[15:8]							
0x0127	DBGBAL	R W		DBGBA[7:0]							
0x0128- 0x012F	Reserved	R W	0	0	0	0	0	0	0	0	
0x0130- 0x013F	Reserved	R W	0	0	0	0	0	0	0	0	

Figure 7-2. Quick Reference to DBG Registers

#### S12Z DebugLite (S12ZDBGV3)

Table 7-22 shows the effect for RWE and RW on the comparison conditions. These bits are ignored if INST is set, as matches based on instructions reaching the execution stage are data independent.

RWE Bit	RW Bit	RW Signal	Comment
0	х	0	RW not used in comparison
0	х	1	RW not used in comparison
1	0	0	Write match
1	0	1	No match
1	1	0	No match
1	1	1	Read match

Table 7-22. Read or Write Comparison Logic Table

## 7.3.2.13 Debug Comparator B Address Register (DBGBAH, DBGBAM, DBGBAL)



Figure 7-16. Debug Comparator B Address Register

Read: Anytime.

Write: If DBG not armed.

### Table 7-23. DBGBAH, DBGBAM, DBGBAL Field Descriptions

Field	Description
23–16 DBGBA [23:16]	<ul> <li>Comparator Address Bits [23:16]— These comparator address bits control whether the comparator compares the address bus bits [23:16] to a logic one or logic zero.</li> <li>0 Compare corresponding address bit to a logic zero</li> <li>1 Compare corresponding address bit to a logic one</li> </ul>
15–0 DBGBA [15:0]	<ul> <li>Comparator Address Bits[15:0]— These comparator address bits control whether the comparator compares the address bus bits [15:0] to a logic one or logic zero.</li> <li>0 Compare corresponding address bit to a logic zero</li> <li>1 Compare corresponding address bit to a logic one</li> </ul>

# Chapter 8 ECC Generation Module (SRAM\_ECCV2)

Rev. No. (Item No.)	Date	Sections Affected	Substantial Change(s)		
V01.00	26-Jul11	all	Initial version V1		
V02.00	10-May-12	all	Initial version V2, added support for max access width of 2 byte		

### Table 8-1. Revision History Table

# 8.1 Introduction

The purpose of ECC logic is to detect and correct as much as possible memory data bit errors. These soft errors, mainly generated by alpha radiation, can occur randomly during operation. "Soft error" means that only the information inside the memory cell is corrupt; the memory cell itself is not damaged. A write access with correct data solves the issue. If the ECC algorithm is able to correct the data, then the system can use this corrected data without any issues. If the ECC algorithm is able to detect, but not correct the error, then the system is able to ignore the memory read data to avoid system malfunction.

The ECC value is calculated based on an aligned 2 byte memory data word. Depending on the device integration, the maximum supported access width can be 2 or 4 bytes. Please see the device overview section for the information about the maximum supported access width on the device.

In a system with a maximum access width of 2 bytes, a 2 byte access to a 2 byte aligned address is classed as an aligned access. If the system supports a 4-byte access width, then a 2-byte access to a 2 byte aligned address or a 4 byte access to a 4 byte aligned address are classed as aligned accesses. All other access types are classed as non-aligned accesses. A non-aligned write access requires a read-modify-write operation, for more details please see section The ECC algorithm is able to detect and correct single bit ECC errors. Double bit ECC errors will be detected but the system is not able to correct these errors. This kind of ECC code is called SECDED code. This ECC code requires 6 additional parity bits for each 2 byte data word.

## 8.1.1 Features

The SRAM\_ECC module provides the ECC logic for the system memory based on a SECDED algorithm. The SRAM\_ECC module includes the following features:

- SECDED ECC code
  - Single bit error detection and correction per 2 byte data word

Field	Description
1 RTIOSCSEL	RTI Clock Select— RTIOSCSEL selects the clock source to the RTI. Either IRCCLK or OSCCLK. Changing the RTIOSCSEL bit re-starts the RTI time-out period. RTIOSCSEL can only be set to 1, if UPOSC=1. UPOSC= 0 clears the RTIOSCSEL bit. 0 RTI clock source is IRCCLK. 1 RTI clock source is OSCCLK.
0 COP OSCSEL0	COP Clock Select 0 — COPOSCSEL0 and COPOSCSEL1 combined determine the clock source to the COP (see also Table 9-8) If COPOSCSEL1 = 1, COPOSCSEL0 has no effect regarding clock select and changing the COPOSCSEL0 bit does not re-start the COP time-out period. When COPOSCSEL1=0,COPOSCSEL0 selects the clock source to the COP to be either IRCCLK or OSCCLK. Changing the COPOSCSEL0 bit re-starts the COP time-out period. COPOSCSEL0 can only be set to 1, if UPOSC=1. UPOSC= 0 clears the COPOSCSEL0 bit. 0 COP clock source is IRCCLK. 1 COP clock source is OSCCLK

### Table 9-8. COPOSCSEL1, COPOSCSEL0 clock source select description

COPOSCSEL1	COPOSCSEL0	COP clock source
0	0	IRCCLK
0	1	OSCCLK
1	х	ACLK

## 10.5.2.17 ADC Command Register 2 (ADCCMD\_2)

A command which contains reserved bit settings causes the error flag CMD\_EIF being set and ADC cease operation.

Module Base + 0x0016



### Figure 10-20. ADC Command Register 2 (ADCCMD\_2)

<sup>1</sup> Only available on ADC12B\_LBA V2 and V3 (see Table 10-2 for details)

### Read: Anytime

Write: Only writable if bit SMOD\_ACC is set

(see also Section 10.5.2.2, "ADC Control Register 1 (ADCCTL\_1) bit SMOD\_ACC description for more details)

#### Table 10-25. ADCCMD\_2 Field Descriptions

Field	Description					
15-11 SMP[4:0]	Sample Time Select Bits — These four bits select the length of the sample time in units of ADC conversion clock cycles. Note that the ADC conversion clock period is itself a function of the prescaler value (bits PRS[6:0]). Table 10-26 lists the available sample time lengths.					
	ADC12B_LBA V2 and V3 (includes OPT[3:2])					
10-9 OPT[3:2]	<b>Option Bits</b> — These two option bits can be used to control a SoC level feature/function. These bits are used together with Option bits OPT[1:0]. Please refer to the device reference manual for details of the feature/functionality controlled by these bits.					

### NOTE

If bit SMOD\_ACC is set modifying this register must be done carefully only when no conversion and conversion sequence is ongoing.

SMP[4]	SMP[3]	SMP[2]	SMP[1]	SMP[0]	Sample Time in Number of ADC Clock Cycles
0	0	0	0	0	4
0	0	0	0	1	5
0	0	0	1	0	6
0	0	0	1	1	7

#### Table 10-26. Sample Time Select

MC912ZVL Family Reference Manual, Rev. 2.41

# **13.3 Memory Map and Register Definition**

This section provides a detailed description of all registers accessible in the MSCAN.

# 13.3.1 Module Memory Map

Figure 13-3 gives an overview on all registers and their individual bits in the MSCAN memory map. The *register address* results from the addition of *base address* and *address offset*. The *base address* is determined at the MCU level and can be found in the MCU memory map description. The *address offset* is defined at the module level.

The MSCAN occupies 64 bytes in the memory space. The base address of the MSCAN module is determined at the MCU level when the MCU is defined. The register decode map is fixed and begins at the first address of the module address offset.

The detailed register descriptions follow in the order they appear in the register map.

Field	Description				
1 OVRIF	Overrun Interrupt Flag — This flag is set when a data overrun condition occurs. If not masked, an error interruptis pending while this flag is set.0No data overrun condition1A data overrun detected				
0 RXF <sup>2</sup>	<ul> <li>Receive Buffer Full Flag — RXF is set by the MSCAN when a new message is shifted in the receiver FIFO. This flag indicates whether the shifted buffer is loaded with a correctly received message (matching identifier, matching cyclic redundancy code (CRC) and no other errors detected). After the CPU has read that message from the RxFG buffer in the receiver FIFO, the RXF flag must be cleared to release the buffer. A set RXF flag prohibits the shifting of the next FIFO entry into the foreground buffer (RxFG). If not masked, a receive interrupt is pending while this flag is set.</li> <li>No new message available within the RxFG</li> <li>The receiver FIFO is not empty. A new message is available in the RxFG</li> </ul>				

Table 13-11. CANRFLG Register Field Descriptions (continued)

<sup>1</sup> Redundant Information for the most critical CAN bus status which is "bus-off". This only occurs if the Tx error counter exceeds a number of 255 errors. Bus-off affects the receiver state. As soon as the transmitter leaves its bus-off state the receiver state skips to RxOK too. Refer also to TSTAT[1:0] coding in this register.

<sup>2</sup> To ensure data integrity, do not read the receive buffer registers while the RXF flag is cleared. For MCUs with dual CPUs, reading the receive buffer registers while the RXF flag is cleared may result in a CPU fault condition.

## 13.3.2.6 MSCAN Receiver Interrupt Enable Register (CANRIER)

This register contains the interrupt enable bits for the interrupt flags described in the CANRFLG register.

Access: User read/write<sup>1</sup> Module Base + 0x0005 7 6 5 4 3 2 0 1 R WUPIE CSCIE RSTATE1 RSTATE0 TSTATE1 TSTATE0 **OVRIE RXFIE** W Reset: 0 0 0 0 0 0 0 0

### Figure 13-9. MSCAN Receiver Interrupt Enable Register (CANRIER)

<sup>1</sup> Read: Anytime

Write: Anytime when not in initialization mode

### NOTE

The CANRIER register is held in the reset state when the initialization mode is active (INITRQ=1 and INITAK=1). This register is writable when not in initialization mode (INITRQ=0 and INITAK=0).

The RSTATE[1:0], TSTATE[1:0] bits are not affected by initialization mode.

# 15.1.2 Modes of Operation

Stop: Timer is off because clocks are stopped.

Freeze: Timer counter keeps on running, unless TSFRZ in TSCR1 is set to 1.

Wait: Counters keeps on running, unless TSWAI in TSCR1 is set to 1.

Normal: Timer counter keep on running, unless TEN in TSCR1 is cleared to 0.

## 15.1.3 Block Diagrams



Figure 15-1. TIM16B6CV3 Block Diagram

# 17.4.2 PWM Channel Timers

The main part of the PWM module are the actual timers. Each of the timer channels has a counter, a period register and a duty register (each are 8-bit). The waveform output period is controlled by a match between the period register and the value in the counter. The duty is controlled by a match between the duty register and the counter value and causes the state of the output to change during the period. The starting polarity of the output is also selectable on a per channel basis. Shown below in Figure 17-16 is the block diagram for the PWM timer.



PWMEx

Figure 17-16. PWM Timer Channel Block Diagram

# 17.4.2.1 PWM Enable

Each PWM channel has an enable bit (PWMEx) to start its waveform output. When any of the PWMEx bits are set (PWMEx = 1), the associated PWM output signal is enabled immediately. However, the actual PWM waveform is not available on the associated PWM output until its clock source begins its next cycle due to the synchronization of PWMEx and the clock source. An exception to this is when channels are concatenated. Refer to Section 17.4.2.7, "PWM 16-Bit Functions" for more detail.

## NOTE

The first PWM cycle after enabling the channel can be irregular.

- For channels 0, 1, 4, and 5 the clock choices are clock A.
- For channels 2, 3, 6, and 7 the clock choices are clock B.

# 17.6 Interrupts

The PWM module has no interrupt.

# 21.2.2 LGND — LIN Ground Pin

This pin is the device LIN ground connection. It is used to sink currents related to the LIN Bus pin. A de-coupling capacitor external to the device (typically 220 pF, X7R ceramic) between LIN and LGND can further improve the quality of this ground and filter noise.

# 21.2.3 VLINSUP — Positive Power Supply

External power supply to the chip. The VLINSUP supply mapping is described in device level documentation.

# 21.2.4 LPTxD — LIN Transmit Pin

This pin can be routed to the SCI, LPDR1 register bit, an external pin, or other options. Please refer to the PIM chapter of the device specification for the available routing options.

This input is only used in normal mode; in other modes the value of this pin is ignored.

## 21.2.5 LPRxD — LIN Receive Pin

This pin can be routed to the SCI, an external pin, or other options. Please refer to the PIM chapter of the device specification for the available routing options.

In standby mode this output is disabled, and sends only a short pulse in case the wake-up functionality is enabled and a valid wake-up pulse was received in the LIN Bus.

# 21.3 Memory Map and Register Definition

This section provides a detailed description of all registers accessible in the LIN Physical Layer.

## 21.3.1 Module Memory Map

A summary of the registers associated with the S12LINPHYV2 module is shown in Table 21-2. Detailed descriptions of the registers and bits are given in the subsections that follow.

## NOTE

Register Address = Module Base Address + Address Offset, where the Module Base Address is defined at the MCU level and the Address Offset is defined at the module level.

#### Flash Module (S12ZFTMRZ)



Figure 22-30. Generic Flash Command Write Sequence Flowchart

#### **MCU Electrical Specifications**

**ACMP Electrical Specifications** 

Table I-2. Static Electrica	Characteristics of the analog	comparator - ACMP
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Characteristics noted under conditions  $3.20V \le V_{DDA} \le 5.15V$ ,  $-40^{\circ}C \le T_J \le 175^{\circ}C^1$  unless otherwise noted. Typical values noted reflect the approximate parameter mean at  $T_A = 25^{\circ}C^2$  under nominal conditions unless otherwise noted.

Num	Ratings	Symbol	Min	Тур	Max	Unit
6	Input Hysteresis in run mode • [ACHYS] = 00 • [ACHYS] = 01 • [ACHYS] = 10 • [ACHYS] = 11	V <sub>ACMP_hyst</sub>	-3 -10 -30 -50	-12 -24 -60 -125	-22 -40 -100 -200	mV mV mV mV
7	Common Mode Input range • V <sub>ACMP_0</sub> • V <sub>ACMP_1</sub> • V <sub>acmpi_0</sub> • V <sub>acmpi_1</sub>	V <sub>ACMP_in</sub>	0	V <sub>DDA</sub> / 2	V <sub>DDA</sub>	V

 $^{1}$  T<sub>J</sub>: Junction Temperature  $^{2}$  T<sub>A</sub>: Ambient Temperature



